Abstract

AN APPARATUS FOR ELECTROPLATING A TOOLING FOR USE IN SEMICONDUCTOR DEVICE ENCAPSULATION

An apparatus is disclosed for electroplating an inside wall of a transfer mold, the transfer mold being suitable for use in semiconductor device encapsulation. Specifically, the apparatus comprises a fixture, as well as a through-hole in the fixture for receiving an electrode to electroplate the inside wall of the transfer mold. In particular, the through-hole is configured to receive the electrode in a slide-fit to form a mutual interference fit for securing the electrode to the fixture. Upon fitting the electrode into the through-hole, the apparatus can then be used to electroplate the inside wall of the transfer mold by introducing the electrode into the space adjacent to the inside wall of the transfer mold. A device for use as an electrode in the apparatus is also disclosed.

[FIG. 2]